

## 64GB (2x32GB) Kit Computer memory DDR3 for ORACLE SUN Fire X4470 M2 RDIMM





# Your benefits ✓ verified quality memory ✓ 5 years warranty Warranty details see last page ✓ 100% compatible ✓ free support on our hotline ✓ fast delivery

#### PHS-memory® - computer memory with 100% quality

- many years of IT competence
- Free support for optimal configuration and product selection
- High availability through professional warehouse management
- Fast delivery in throughout Europe
- Short response times and professional order processing due to full digitalization throughout the entire process with complete traceability
- Incoming goods inspection include checks of the DRAMs, PCBs and the programmed SPDs in order to exclude possible errors (Controlled BOM).
- PHS-memory® brand memories guarantee 100% compatibility to the specified system.
- PHS-memory® memories can be used together with existing memories in the device depends on to the configuration rules of the system.
- The "fallback option" in the SPD of PHS-memory® allows DRAMs with higher clock rates to be operated together with older memory modules with lower clock rates within the system.
- Products with unique serial number for service and warranty
- Pre-sales and after-sales support by technically trained personnel



#### Memory Specification



Memory technologyDDR3ECC supportyesJEDEC NormPC3-10600RDRAM Organization2Gx4Rank4Rx4 (4DRx4 DDP)TypeRDIMM (ECC Registered)Number of pins240 Pin DIMMMemory data transfer rate1333MHz @ CL9SpecialityDDPBoard dimensions133,35 x 30 (LxB mm)Operating temperature0° C - 85° CStorage temperature-40° C - +95° CRoHS compliantyes	Memory size	32GB		
JEDEC Norm  PC3-10600R  DRAM Organization  2Gx4  Rank  4Rx4 (4DRx4 DDP)  Type  RDIMM (ECC Registered)  Number of pins  240 Pin DIMM  Memory data transfer rate  1333MHz @ CL9  Speciality  DDP  Board dimensions  133,35 x 30 (LxB mm)  Operating temperature  0° C - 85° C  Storage temperature  -40° C - +95° C  RoHS compliant  yes	Memory technology	DDR3		
DRAM Organization2Gx4Rank4Rx4 (4DRx4 DDP)TypeRDIMM (ECC Registered)Number of pins240 Pin DIMMMemory data transfer rate1333MHz @ CL9SpecialityDDPBoard dimensions133,35 x 30 (LxB mm)Operating temperature0° C - 85° CStorage temperature-40° C - +95° CRoHS compliantyes	ECC support	yes		
Rank4Rx4 (4DRx4 DDP)TypeRDIMM (ECC Registered)Number of pins240 Pin DIMMMemory data transfer rate1333MHz @ CL9SpecialityDDPBoard dimensions133,35 x 30 (LxB mm)Operating temperature0° C - 85° CStorage temperature-40° C - +95° CRoHS compliantyes	JEDEC Norm	PC3-10600R		
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Operating temperature 0° C - 85° C  Storage temperature -40° C - +95° C  RoHS compliant yes	Speciality	DDP		
Storage temperature -40° C - +95° C  RoHS compliant yes	Board dimensions	133,35 x 30 (LxB mm)		
RoHS compliant yes	Operating temperature	0° C - 85° C		
	Storage temperature	-40° C - +95° C		
<b>SMI</b> SD466070	RoHS compliant	yes		
3F400070	SKU	SP466070		
<b>EAN</b> 4067488295805	EAN	4067488295805		

### overRAMing - maximize your RAM



Most systems - including the ORACLE SUN Fire X4470 M2 - can be upgraded with more memory than originally specified by the device manufacturer.

Therefore, our memory specialists continuously analyze new memory solutions in selected systems. Due to improved manufacturing technologies, new memories with higher performance and capacity will be tested for stability and functionality.

Then the new memory solutions are released for the respective systems. Use the benefits of larger computer memory capacity with the PHSmemory® overRAMing memory solutions.

https://www.phs-memory.com/-BOR

Note: The module specified in this datasheet is one of several possible configurations available under this part number.

Some details may differ from the specifications described here and the illustration, but have no negative influence on the functionality.



#### System Specifications

The memory is 100% compatible with this sytem:

System manufacturer	ORACLE
Device type	Server
Device family	SUN Server
Device series	Fire X Serie
Device name	SUN Fire X4470 M2
Maximum memory*	2TB / 1TB according to manufacturer
Number of memory sockets	64

<sup>\*</sup> The specifications for the maximum memory upgrade may differ from those of the manufacturer ORACLE. Often the information given in the manual for the maximum memory upgrade is not up to date. New memory technologies, bios updates or newer software versions often allow the use of memory modules with a higher capacity than specified by the manufacturer with the same performance and stability.

Memory modules with our overRAMing-symbol are approved by us for maximum memory expansion

#### Information on memory allocation

#### Computer memory configuration

Our memory team will be happy to help you choose the right memory and configure your server.

#### Principles of memory assembly

- The memory slots are organized in groups of 4
- Eine Bestückung with weniger als 4 memoryn ist nicht empfehlenswert
- Es können nur die memorysteckplätze genutzt werden, bei denen die jeweilige CPU vorhanden ist.

#### Memory configuration for good system performance

- Optimale Performance erreichen Sie bei Einsatz of 8 or 16 identischen memory pro CPU. The memories should be used per CPU via two memory boards
- The memory should be populated identically per CPU (mirrored to the other CPU).

#### Information on memory installation

- Turn off the system
- Remove the plug of the power supply unit (if connected)
- Remove the battery, according to the user manual of the system
- Always ground yourself before touching electronic components
- Protect the memory module from static voltages:
  - Do not touch the gold pins of the memory module
  - Only touch the sides of the memory module
  - Use a grounding strap and/or ESD glove if possible

General installation instructions are supplied by E-Mail.



#### Further memory options for ORACLE SUN Fire X4470 M2

Size	SKU	Technology	Туре	Number of pins	Brand	Reference no.
8GB	SP236686	DDR3	RDIMM (ECC Registered)	240 Pin DIMM	PHS-memory®	
16GB	SP236685	DDR3	RDIMM (ECC Registered)	240 Pin DIMM	PHS-memory®	
32GB	SP466070	DDR3	RDIMM (ECC Registered)	240 Pin DIMM	PHS-memory®	

#### PHS-memory® warranty

Every PHS-memory® is equipped with a 5-years-warranty of perfect operation. If the RAM module is defective or fails within 5 years of purchase when used properly, you will receive an appropriate RAM module free of charge. If a suitable memory module is no longer available, we will refund the purchase price.





#### Contact Information

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All information without guarantee. Technical changes and errors excepted. You can find current price information in our online shop at https://www.phs-memory.com